

FORM PTO-1595

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(Rev.6-93)

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1. Name of conveying party(ies):  
Lawrence A. Clevenger; Matthew E. Colburn;  
Louis C. Hsu; and Wai-Kin Li  
Additional name(s) of conveying party(ies)  
attached?  
Yes  No

2. Name and address of receiving party(ies)  
Name: International Business Machines Corporation  
Internal Address:  
Street Address: New Orchard Road  
City: Armonk State: NY ZIP: 10504  
Additional name(s) & address(es) attached?  Yes  No

3. Nature of conveyance:  
 Assignment  Merger  
 Security Agreement  Change of Name  
 Other  
Execution Date: January 30, 2007  
January 30, 2007  
January 31, 2007  
January 30, 2007

4. Application number(s) or patent number(s):  
If this document is being filed together with a new application, the execution date of the application is:  
A. Patent Application No.(s) 11/670,524, Filed February 2, 2007 B. Patent No.(s)  
Additional numbers attached? Yes  No

5. Name and address of party to whom  
correspondence concerning document should be  
mailed:  
Name: Paul J. Otterstedt  
Internal Address: Ryan, Mason & Lewis, LLP  
Street Address: 1300 Post Road, Suite 205  
City: Fairfield State: CT ZIP: 06824

6. Total number of applications and patents  
involved: 1  
7. Total Fee (37 CFR 3.41)..... \$ 40.00  
 Enclosed  
 Authorized to be charged to deposit account  
8. Deposit account number 50-0510

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*To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.*

Paul J. Otterstedt  
Reg. No. 37,411

*Paul J. Otterstedt*  
Signature

February 6, 2007  
Date

Total number of pages including cover sheet, attachments, and document: 5

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YOR920060417US1

PATENT

Attorney Docket No : YOR920060417US1

**ASSIGNMENT**

Whereas, we

Inventor  
and City

- (1) **Lawrence A. Clevenger** of LaGrangeville  
County of Dutchess and State of New York
- (2) **Matthew E. Colburn** of Hopewell Junction  
County of Dutchess and State of New York
- (3) **Louis C. Hsu** of Fishkill  
County of Dutchess and State of New York
- (4) **Wai-Kin Li** of Beacon  
County of Dutchess and State of New York

have invented certain improvements in

**TITLE MICROELECTRONIC CIRCUIT STRUCTURE WITH LAYERED LOW DIELECTRIC  
CONSTANT REGIONS AND METHOD OF FORMING SAME**

executed by me on even date herewith,

DATE THAT INVENTORS SIGNED THE (1) 1/30, 2007 (2) 1/30, 2007 (3) \_\_\_\_\_, 2007,  
(4) 1/30, 2007

**DECLARATION**

Whereas, INTERNATIONAL BUSINESS MACHINES CORPORATION, a corporation of New York, having a place of business at New Orchard Road, Armonk, New York 10504, (hereinafter called IBM) desires to acquire the entire right, title and interest in the said application and invention, and to any United States and foreign patents to be obtained therefor.

Now therefore, for a valuable consideration, receipt whereof is hereby acknowledged, we the above named, hereby sell, assign, and transfer to IBM, its successors and assigns, the entire right, title and interest in the said application and invention therein disclosed for the United States and foreign countries, and all rights of priority resulting from the filing of said United States application, and we request the Commissioner of Patents to issue any Letters Patent granted upon the inventions set forth in said application to IBM, its successors and assigns; and we hereby agree that IBM may apply for foreign Letters Patent on said invention and we will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by IBM.

Signed  
CITY (1) at Hopewell Junction, NY Lawrence A. Clevenger SIGNATURE  
DATE on 1/30, 2007, (Lawrence A. Clevenger) INVENTOR  
FIRST NAME MIDDLE INITIAL LAST NAME

Attorney Docket No : YOR920060417US1

Signed  
CITY and (2) at Yorktown Heights, NY Matthew E Colburn SIGNATURE  
DATE on 1/30, 2007, (Matthew E Colburn) INVENTOR  
FIRST NAME MIDDLE INITIAL LAST NAME

Signed  
CITY and (3) at Hopewell Junction, NY \_\_\_\_\_ SIGNATURE  
DATE on \_\_\_\_\_, 2007, (Louis C Hsu) INVENTOR  
FIRST NAME MIDDLE INITIAL LAST NAME

Signed  
CITY and (4) at Hopewell Junction, NY Wai-Kin Li SIGNATURE  
DATE on 1/30, 2007, (Wai-Kin Li) INVENTOR  
FIRST NAME MIDDLE INITIAL LAST NAME

Ryan, Mason & Lewis, LLP  
1300 Post Road, Suite 205  
Fairfield, CT 06824  
(203) 255-6560

Attorney Docket No : YOR920060417US1

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Whereas, we

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County of Dutchess

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and State of New York

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County of Dutchess

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and State of New York

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and State of New York

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TITLE

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FIRST NAME MIDDLE INITIAL LAST NAME

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Attorney Docket No : YOR920060417US1

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DATE on 1-31, 2007, (Louis C. Hsu) INVENTOR  
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CITY and (4) at Hopewell Junction, NY \_\_\_\_\_ SIGNATURE  
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